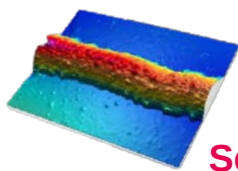
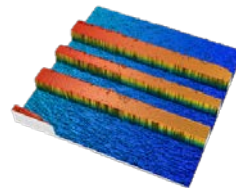


SURFIEW 500



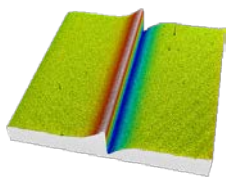
Semiconductor

Stud Bump	지름, 높이, 부피, 거칠기, 각도
CMP	Warpage, 거칠기
CVD	거칠기
Wafer	Warpage, 스크래치, 거칠기



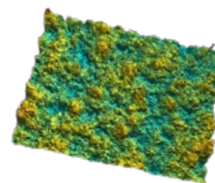
PCB

Substrate (Pad, Trace, Space, Anchor, Land, Ball Pad, Via Hole, Dimple, SR)	높이, 폭, 깊이, 지름, 두께, 부피, 거칠기, Roundness
BGA	Ball 높이, 지름, Coplanarity



Display

Photo Space	지름, 높이, 폭, 부피
RGB	두께, 거칠기, BM 두께
TFT Pattern	높이, 폭, 거칠기
BLU	각도, 폭, 높이, 거칠기
Metal Jet	폭, 높이, 각도, 거칠기
Glass	Defect 형태, 폭, 높이,
OLED	증착 높이, 각도, 부피



기타

MEMS	높이, 폭
Precision machine part	거칠기, 높이, 폭
Laser Marking	깊이, 부피
Inkjet	부피, 높이, 면적
Micro Lens	곡률, 높이
RFID	높이, 폭, 거칠기

Specification

SURFIEW 500

Vertical Resolution	VSI,VEI < 0.5nm, VPI < 0.1nm
Lateral Resolution	0.05~7.2um(Depends on magnification)
Height Repeatability	≤0.3% @ 1σ
Objective Lens	1 Selectable(Manual)
Zoom Lens	1 Selectable(1.0x @ Manual)
Camera Format	1/2" Mono Camera
Scan Method	Piezo Actuator @ SGS Closed loop
PZT Scan Range	≤100um
Scan Speed	7.5um/sec(1x) / 22.5um/sec(3x)
Illumination	White LED
Filter	Visible/Bandpass Filter(Manual)
X/Y Axis Stroke	25mm(X) x 13mm(Y)
Z Aixs Stroke	13mm
Tilt Aixs Stroke	± 2°
Work Table Size	80mm X 80mm
Max Workpiece Load	≤ 1kg
Layout Size	1100mm(W) x 700mm(D) x 1450mm(H)
Software	Surface View/Surface MAP@ Window10 (64bit)
Stitching	NO
Vibration Isolation Platform	Passive Type(Vertical Resonance: 2.5Hz)
Input Power	2φ,110V/220V(± 10%), 50/60Hz

Option

Interference Lens	2.5x, 5.0x, 10x, 20x, 50x, 100x
Objective Lens	2.5x, 5.0x, 10x, 20x, 50x, 100x
Zoom Lens	0.55x, 0.75x, 1.0x, 1.5x, 2.0x
PZT Scan Range	≤250um
Camera Format	2/3" or 1" Mono Camera
Work Table	Vacuum Table, Rotation Table